

Silicon thermal transfer compound

Thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink.



art. no.	container	delivery quantity [g]
WLP 004	box	4
WLP 035	box	35
WLP 500	box	500
WLP 300 S	cartridge	300
WLP 500 S	cartridge	500

Silicone-free thermal transfer compound

Thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink.



art. no.	container	delivery quantity [ml]
WLFP 05	syringe	2
WLFP 10	syringe	5
WLFP 20	syringe	10
WLFP 50	syringe	20

Technical data

	WLP	WLFP
composition	silicone oil, inorganic filling material	Silicone free synthetic liquid. Metal oxide filling.
consistance	pastey	pastey
colour	white	white-grey
tightness	1.1 g/cm ³	ca. 2 g/cm ³
thermal conductivity W/mK	0.61	>0.7
specific electrical resistance	>10 ¹² Ω/cm	>10 ¹² Ω/cm
flashpoint	none (DIN 53213)	of the basic oil >280 °C (ISO 2592)
drop point	>260 °C	—
thermal resistance	no bleeding at (4 h / 200°C)	<1 % (96 h / 200 °C)
temperature range	-70 °C ... +250 °C	-40 °C ... +150 °C
acid number	< 0.01 mg KOH/g	—
solubility in water	insoluble	insoluble

Graphit thermal transfer compound



art. no.	container	delivery quantity [ml]
WLPG 02	syringe	2
WLPG 05	syringe	5
WLPG 10	syringe	10
WLPG 20	syringe	20

Technical data

	WLPG
composition	graphite filler, silicone free, organic filling material, biodegradable matrix based on oil
consistence	pastey
colour	black
tightness	>1.25 g/cm ³
thermal conductivity	10.5 W/mK
specific electrical resistance	10 ⁵ Ω/cm (typical)
breakdown voltage	not applicable, because conducting
flashpoint	for oil DIN 51755, 321 °C
temperature range	-40 °C ... +320 °C
solubility in water	soluble